

Amendments to the Specification:

Page 1, please replace the second full paragraph with the following amended paragraph:

Japanese Application Patent Laid-open Publication No. Hei 7-273237A discloses the semiconductor device in which a hollow is provided around an IC chip and sealed [[up]] with a structure composed of a first cap, a molded resin, and a second cap. The molded resin is cured by baking after it is covered with the second cap. Since the device has the hollow around the IC chip, it is possible to prevent IC bonding wires from being cut by thermal stress caused by plastic molding. Furthermore, deterioration of the electrical characteristic can be prevented in comparison with [[the]] a device in which the IC chip is directly covered by resin, by making a hollow structure around the IC chip.

Page 6, please replace the third full paragraph with the following amended paragraph:

FIG. 5 illustrates another embodiment, which differs from the embodiment shown in FIG. 4 in that a separate structure is employed for the antenna pattern 2. That is, a substrate which carries the antenna pattern 2a is formed separately from the case 42. This configuration increases the flexibility of the design for antenna characteristic.

Page 7, please replace the third full paragraph with the following amended paragraph:

The present invention, which has been described above, provides good electrical characteristic of millimeter waves since it can make a hollow structure around MMICs on a multilayer substrate. Furthermore, since the [[whole]] entire space within a case [[in]] which houses electric parts is covered with a gelled organic resin which has moisture resistance, it is possible to provide a low-cost millimeter wave radar RF module having increased productivity while maintaining the millimeter wave electrical characteristic even though airtightness is not assured.